STPS3150-Y

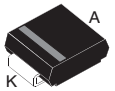
Automotive power Schottky rectifier

Features

- AEC-Q101 qualified
- Negligible switching losses
- Low forward voltage drop for higher efficiency and extented battery life
- Low thermal resistance
- ECOPACK®2 compliant component

Description

Packaged in SMB, this device is intended for use in automotive applications where low drop forward voltage is required to reduce power dissipation.



SMB
STPS3150UY

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	3 A
V_{RRM}	150 V
T_j (max)	175 °C
V_F (max)	0.67 V

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		150	V
$I_{F(AV)}$	Average forward current	T_L = 130 °C δ = 0.5	3	A
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms sinusoidal	80	A
T_{stg}	Storage temperature range		-65 to +175	°C
T_j	Operating junction temperature range(1)		-40 to +175	°C

1. $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction to lead	20	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Typ	Max.	Unit
I_R (1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RRM}$		0.4	2.0	µA
		T_j = 125 °C			0.6	2.0	mA
V_F (2)	Forward voltage drop	T_j = 25 °C	I_F = 3 A		0.78	0.82	V
		T_j = 125 °C			0.63	0.67	
		T_j = 25 °C	I_F = 6 A		0.85	0.89	
		T_j = 125 °C			0.70	0.75	

1. t_p = 5 ms, δ < 2%
2. t_p = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation:
$P = 0.59 \times I_{F(AV)} + 0.023\ I_{F}^{2}{}_{(RMS)}$

Figure 1. Average forward power dissipation versus average forward current

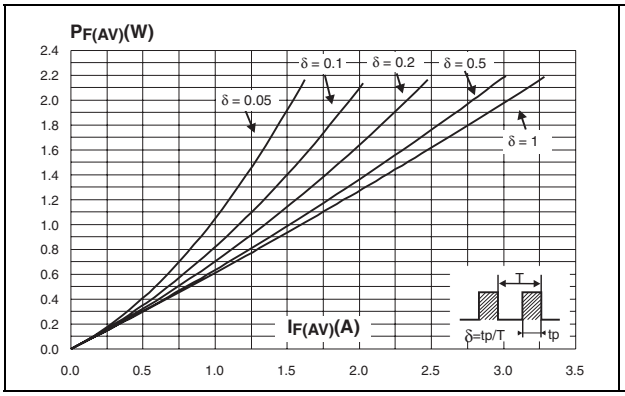


Figure 2. Average forward current versus ambient temperature (δ = 0.5)

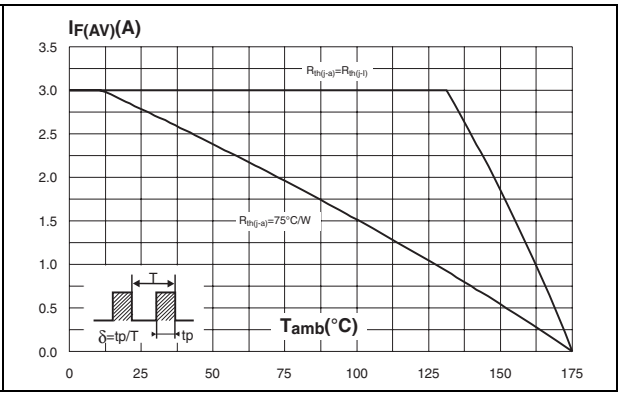


Figure 3. Non repetitive surge peak forward current versus overload duration (maximum values)

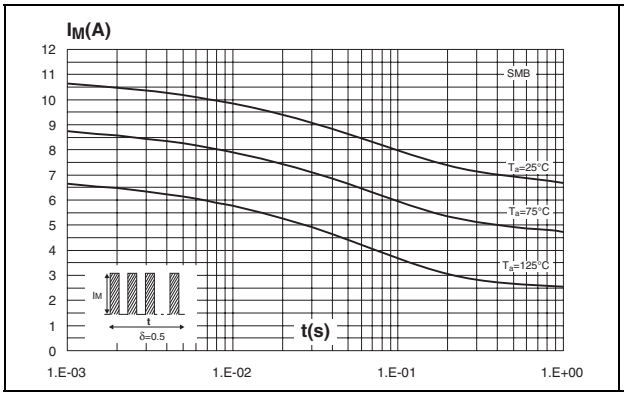


Figure 4. Normalized avalanche power derating versus pulse duration

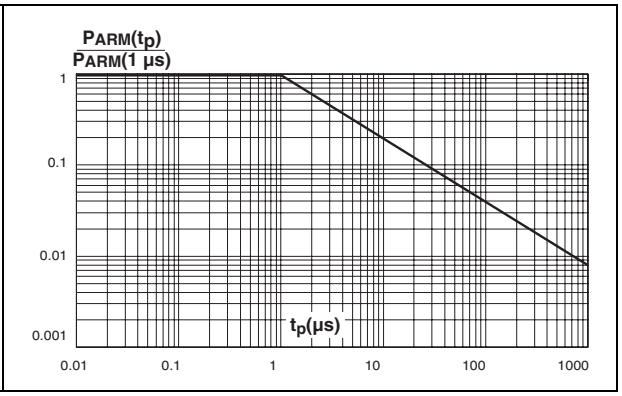


Figure 5. Normalized avalanche power derating versus junction temperature

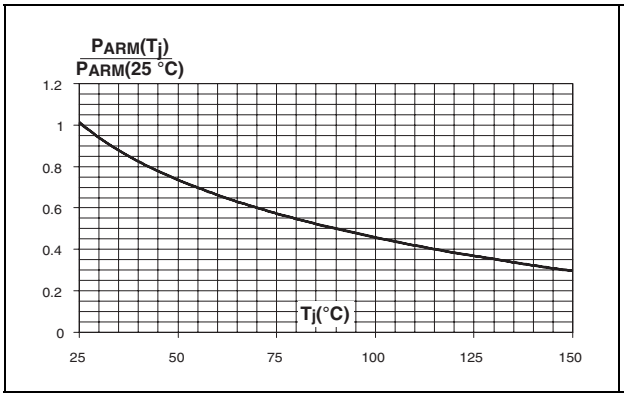


Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration

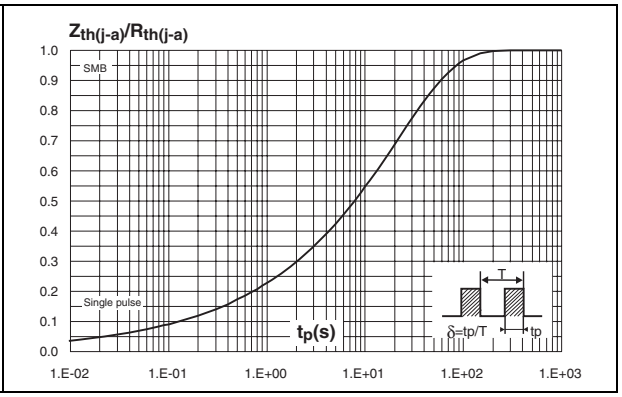


Figure 7. Reverse leakage current versus reverse voltage applied (typical values)

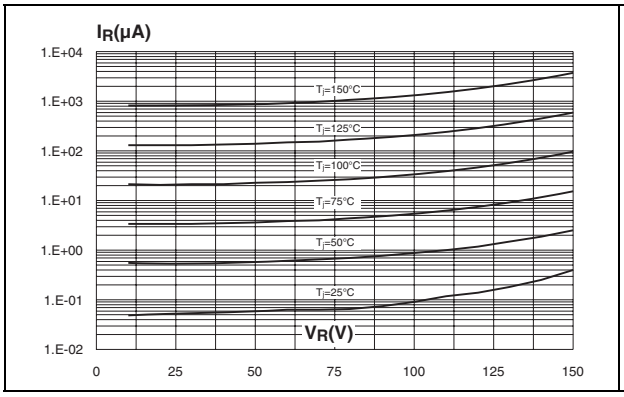


Figure 8. Junction capacitance versus reverse voltage applied (typical values)

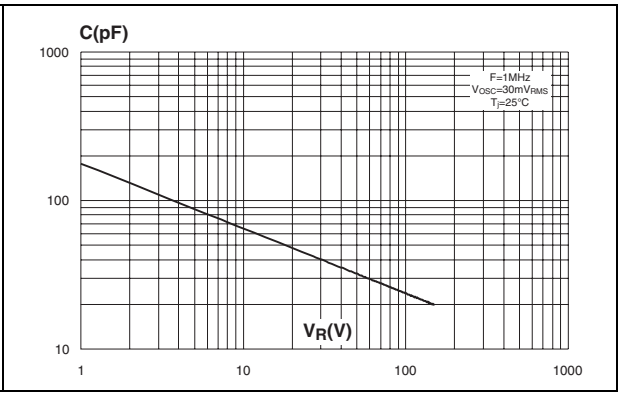


Figure 9. Forward voltage drop versus forward current

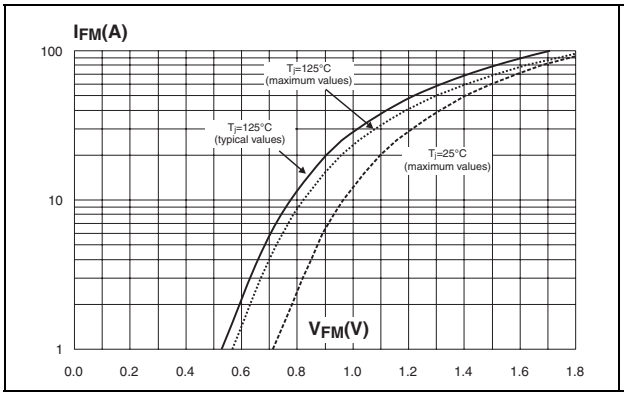


Figure 10. Forward voltage drop versus forward current

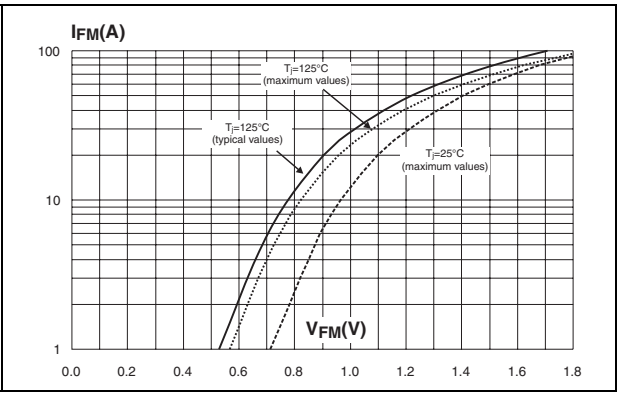
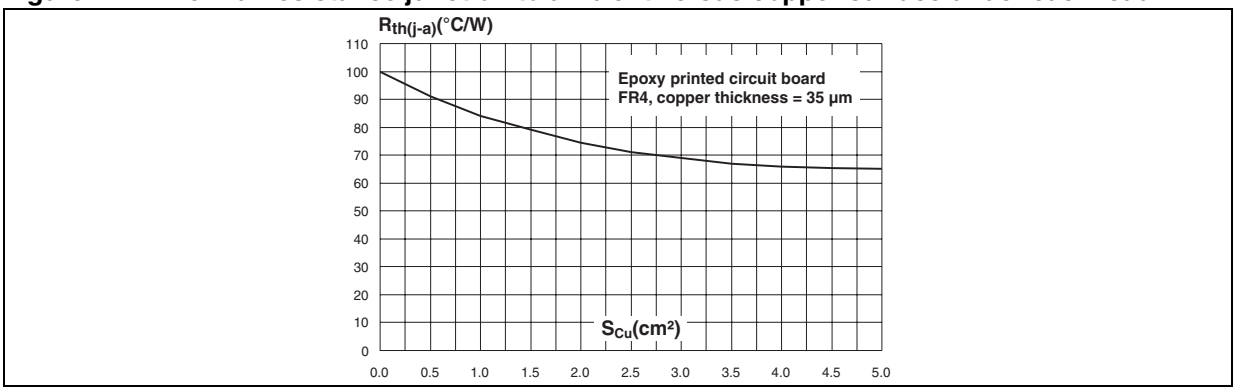


Figure 11. Thermal resistance junction to ambient versus copper surface under each lead

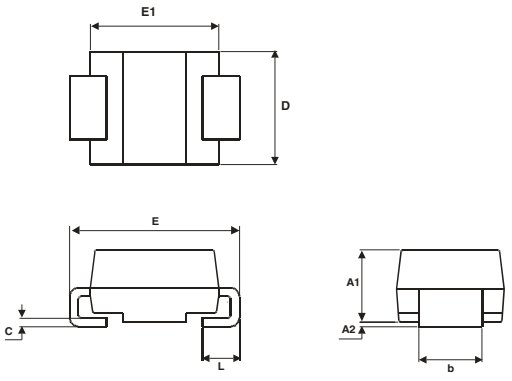


2 Package information

- Epoxy meets UL94, V0
- Lead-free package

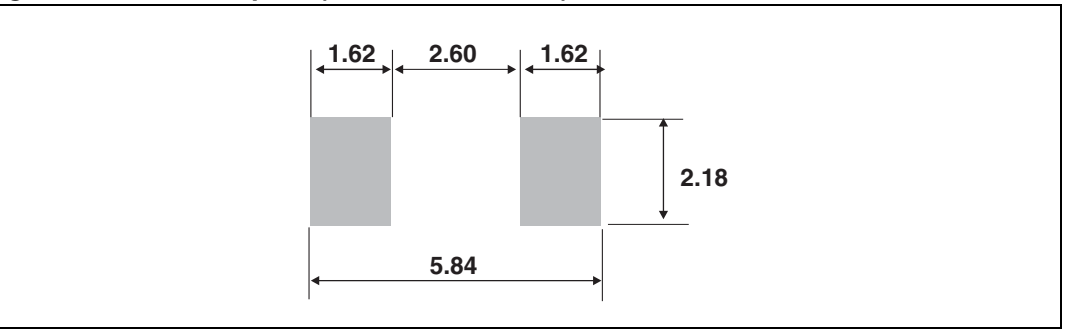
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 5. SMB dimensions



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.50	0.030	0.059

Figure 12. SMB footprint (dimensions in mm)



3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS3150UY	G315Y	SMB	0.107 g	2500	Tape and reel

4 Revision history

Table 7. Document revision history

Date	Revision	Description of Changes
03-Nov-2011	1	Initial release.

Mouser Electronics

Authorized Distributor

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STPS3150UY